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UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.

1. APPLICATION DESIGN MANUFACTURING AND INSPECTION DOCUMENTS.
IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.
IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD.
IPC-A-6006 / ACCEPTABILITY OF PRINTED BOARDS.

2. HOLE SIZE APPLY AFTER PLATING. TOLERANCE +/- .003/-NOMINAL NUMBER AND PROCEED TO IPC 6012 CLASS 2.

3. REGISTRATION TOLERANCE: ARTWORK +/- .002
ALL HOLE CENTERS +/- .005 FROM DIMENSION DATUM.

4. MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.
FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.

5. PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.
MATERIAL: MULTI-LAYER (SEE DETAIL "A")
SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: 0.062 +/-10%

6. MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.

7. SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT).
COLOR=RED (0.001 TO 0.002" THICK OVER METAL).

8. SILKSCREEN BOTH SIDES, USING WHITE NPI LEADFREE.
REGISTRATION TOLERANCE TO BE +/- .005. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.

9. P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.

10. BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH.
MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.

11. BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

12. ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.

13. ALL OUTER LAYERS USING A 12 MIL TRACE WIDTH SHALL BE 50 OHMS SINGLE ENDED, +/-10% TOLERANCE.
ALL INNER & OUTER LAYERS USING A 6 MIL TRACE WIDTH AND 6 MIL SPACING SHALL BE 100 OHMS DIFFERENTIAL, +/-10% TOLERANCE.
INNER LAYER 4 USING A 8.7 MIL TRACE WIDTH SHALL BE 50 OHMS SINGLE ENDED, +/- 10% TOLERANCE.

14. MINIMUM COPPER CONDUCTOR WIDTH IS: 4 MILS.
MINIMUM COPPER SPACING IS: 4 MILS.

15. SMOBC/IMMERSION GOLD: 3-8 uIN OVER 100-200 uIN NICKEL PLATING.

16. ALL 8 MIL, 10MIL & 12MIL HOLES/VIAS TO BE PLATED AND FILLED WITH NON-CONDUCTIVE EPOXY.
FILLED VIAS SHALL BE PLATED AFTER FILLING AND COPLANAR.

17. VENDOR MAY ADD GANG MASK WHERE SOLDER MASK WEB IS LESS THAN .001.

19. PWB MUST BE ROHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY,
MAX REFLOW OF 260 DEGREES C (6 PASSES).

REVISIONS

ZONE	LTR	DESCRIPTION	DATE	APPROVED
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TOP

LAYER 1

Copper Foil 3/8oz / Plate to 1.0oz min Layer 1

370H

LAYER 2

370H

Core 0.014" 1.0oz / 1.0oz Layer 2 & 3

370H

LAYER 3

370H

Pre-preg 0.0089"

LAYER 4

370H

Core 0.014" 1.0oz / 1.0oz Layer 4 & 5

LAYER 5

370H

Pre-preg 0.0074"

LAYER 6

370H

Copper Foil 3/8oz / Plate to 1.0oz min Layer 6

BOTTOM

2.600

2.450

.150

.150

5.580

5.730

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
·	8.0	+0.0/-0.0	PLATED	38
·	10.0	+0.0/-0.0	PLATED	1380
·	12.0	+0.0/-0.0	PLATED	15
·	12.0	+0.0/-0.0	PLATED	1
⦿	15.0	+0.0/-0.0	PLATED	8
⦿	38.0	+0.0/-0.0	PLATED	12
⦿	40.0	+0.0/-0.0	PLATED	14
⦿	43.0	+0.0/-0.0	PLATED	5
⦿	46.0	+0.0/-0.0	PLATED	8
⦿	59.0	+0.0/-0.0	PLATED	11
⦿	67.0	+0.0/-0.0	PLATED	44
@	120.0	+3.0/-3.0	PLATED	2
M	125.0	+0.0/-0.0	PLATED	4
O	140.0	+0.0/-0.0	PLATED	1
P	250.0	+0.0/-0.0	PLATED	2
·	39.0	+0.0/-0.0	NON-PLATED	2

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
FRACTIONS DECIMALS ANGLES
+/- .XX +/- .01
+/- .XXX +/- .005 +/-

MATERIAL

FINISH

DO NOT SCALE DRAWING

CONTRACT NO.

APPROVALS

DRAWN JV SMITH 11-01-11

ENGR JIM SETON 11-01-11

TEXAS INSTRUMENTS INC.

FABRICATION DRAWING
TSW4806 EVM

SIZE B

CODE IDENT NO.

DRAWING NO.

REV. B

SCALE NONE

SHEET 1 OF 1

ART FILM - FABR02

ART FILM - FABR02